

Product features

Broadband, small volume.

Main specifications

Parameters	Min	Typical	Max	Units
Frequency	2	~	6	GHz
IL		0.5		dB
Isolation		20		dB
Input VSWR		1.5		
Output VSWR		1.5		
Amplitude balance			0.2	dB
Phase balance			±3	°

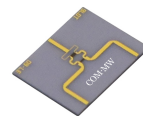
Other parameters

Power Capacity	2W Design assurance
X-Way	2-way
Phase	0°
Impedance	50Ω
Operation Temp.	-40~+70°C Design assurance
Other	Thin film ceramics

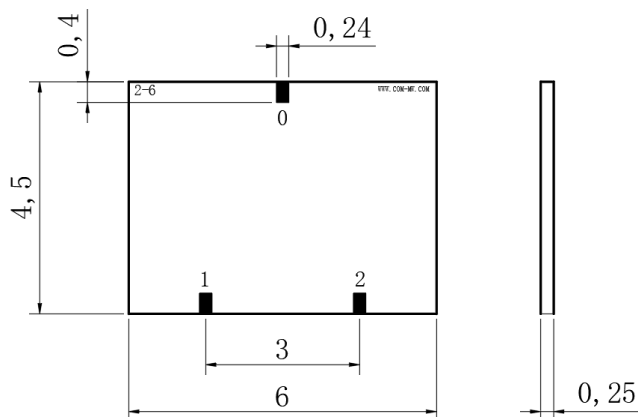
Port Definition

Common port	0
Dispatch Port	1, 2

Reference picture



Configuration(mm)



Note

- 1 The chip is recommended to be used in separate cavities, with a distance of 0.1mm from the sidewall on one side and a distance of 1-2mm from the upper cover on the surface.
- 2 Low stress conductive adhesive (ME8456) is recommended for bonding chips.
- 3 The chip should be installed on a carrier such as molybdenum copper, which is close to the thermal expansion coefficient of ceramics (6.7ppm/C °), with a carrier thickness of ≥ 0.2mm.
- 4 电路板微带线与芯片键合连接时，建议微带键合处采用T型结构进行匹配，尺寸如下：